



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-08-08
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STL135N8F7AG	BSY5*OD88Q52	A	SH1A	2016-08-08
Amount		UoM	Unit type	ST ECOPACK Grade
100.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	6, 5, 1	8	pin	
Comment	Package: POWERFLAT WETTABLE FLANKS SINGLE			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BSYS*OD88Q52					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	10.178	mg	supplier	die	Silicon (Si)	7440-21-3		9.834	mg	966202	98340
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.193	mg	18962	1930
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.054	mg	5306	540
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.005	mg	491	50
die (s)				supplier	metallization	Nickel (Ni)	7440-02-0		0.068	mg	6681	680
die (s)				supplier	metallization	Silver (Ag)	7440-22-4		0.024	mg	2358	240
Leadframe	Copper & its alloys	42.272	mg	supplier	alloy	Copper (Cu)	7440-50-8		41.194	mg	974498	411940
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.969	mg	22923	9690
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.058	mg	1372	580
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.051	mg	1206	510
Soft solder	Solder	11.415	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	10.902	mg	955059	109020
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.285	mg	24967	2850
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.228	mg	19974	2280
Bonding wire & Clip	Precious metals	7.863	mg	supplier	wire	Gold (Au)	7440-57-5		0.058	mg	7376	580
Bonding wire & Clip				supplier	clip	Copper (Cu)	7440-50-8		7.805	mg	992624	78050
encapsulation	Other inorganic materials	28.116	mg	supplier	mold compound	Silica, vitreous	60676-86-0		22.071	mg	784998	220710
encapsulation				supplier	mold compound	epoxy resin	25068-38-6		3.655	mg	129997	36550
encapsulation				supplier	mold compound	phenol resin	9003-35-4		1.687	mg	60001	16870
encapsulation				supplier	mold compound	metal hydroxide	21645-51-2		0.562	mg	19989	5620
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.141	mg	5015	1410
connections coating	Solder	0.156	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.156	mg	1000000	1560